

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

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APPLICABLE STANDARD			
OPERATING TEMPERATURE RANGE OPERATING HUMIDITY RANGE	-35°C TO +85°C(NOTES 1)	STORAGE TEMPERATURE RANGE STORAGE HUMIDITY RANGE	-10°C TO +60°C(NOTES 3)
	20% TO 80%(NOTES 2)		40% TO 70%(NOTES 2)(NOTES 3)
RATING	VOLTAGE	30V AC	DF56※-26S-0.3V(##)
	CURRENT	AWG#42:0.2A AWG#44:0.15A AWG#46:0.1A	THIN COAXIAL CABLE (AWG#42~AWG#46)

SPECIFICATIONS

ITEM	TEST METHOD		REQUIREMENTS	
	QT	AT		
CONSTRUCTION				
GENERAL EXAMINATION	VISUALLY AND BY MEASURING INSTRUMENT.		ACCORDING TO DRAWING.	X X X
MARKING	CONFIRMED VISUALLY.			X X X

ENVIRONMENTAL CHARACTERISTICS

SULFUR DIOXIDE GAS	EXPOSED IN 10-15 PPM 96h.	NO DEFECT SUCH AS CORROSION WHICH IMPAIRS THE FUNCTION OF CONNECTOR.	X	—
RESISTANCE TO SOLDERING HEAT	① BONDING TEMPERATURE: 270°C MAX :5 sec MAX 200°C MIN :30 sec MAX ② MANUAL SOLDERING TEMPERATURE: 350°C, 3sec MAX.	NO DEFORMATION OF CASE OF EXCESSIVE LOOSENESS OF THE TERMINALS.	X	—
SOLDERABILITY	SOLDERED AT SOLDER TEMPERATURE, 245°C, FOR INSERTION DURATION, 5 sec. (Sn-3.0Ag-0.5Cu)	SOLDER SHALL COVER A MINIMUM OF 95% OF THE SURFACE BEING IMMERSUED.	X	—

COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
△				

REMARKS

NOTE1: INCLUDE THE TEMPERATURE RISING BY CURRENT
 NOTE2: NON CONDENSING
 NOTE3: THE TERM "STORAGE" REFERS TO PRODUCTS STORED FOR A LONG PERIOD PRIOR TO MOUNTING AND USE. THE OPERATING TEMPERATURE AND HUMIDITY RANGE COVERS THE NON-CONDUCTING CONDITION OF CONNECTORS AFTER BOARD MOUNTING AND THE TEMPORARY STORAGE CONDITIONS OF TRANSPORTATION, etc
 NOTE4: TEMPERATURE RISE OF CONNECTOR BODY ONLY, AND THAT OF CASE IS NOT INCLUDED.
 Unless otherwise specified, refer to JIS C 5402, IEC60512.

APPROVED	TS. SAKATA	11.04.01
CHECKED	HS. OZAWA	11.03.31
DESIGNED	AH. MIYAZAKI	11.03.31
DRAWN	AH. MIYAZAKI	11.03.31

Note QT: Qualification Test AT: Assurance Test X: Applicable Test DRAWING NO. EL04-329551-01

HRS	SPECIFICATION SHEET		PART NO.		DRAWING NO.		DF56-26P-SHL	
	HIROSE ELECTRIC CO., LTD.	CODE NO.	CL662-5605-4-00	△	1/1			